

In the Specification:

Replace the paragraph between page 4, lines 9-12 with the following:

--In accordance with a further added feature of the invention, the carrier includes a plate made of ceramic, the metal area is applied above the plate, and the metal area serves as a contact area of the chip.--

In the Claims:

Sub B2
Alt B1
Claim 7 (amended). The carrier and the chip configuration according to claim 1, wherein said carrier includes a plate made of ceramic, said metal area is applied above said plate, and said metal area forms a contact area for said chip.